

IN THE CLAIMS:

Please cancel Claim 2 without prejudice to or disclaimer of the subject matter recited therein.

Please amend Claims 1, 5-8 and 10 to read as follows. A marked-up copy of these claims, showing the changes made thereto, is attached. Please note that all claims currently pending in this application are being reproduced below for the Examiner's convenience regardless of whether the claim is being amended.

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1. (Amended) A printed wiring board comprising:

a substrate having two opposite surfaces, a plurality of soldering through holes formed in said substrate so as to open in said opposite surfaces, for inserting leads of an inserted component to be mounted onto the printed wiring board and soldering the inserted component onto said substrate, each of said through holes having an inner peripheral surface, a plurality of lands each formed continuously across said opposite surfaces and the inner peripheral surface of a corresponding one of said through holes, each land having a surface, and at least one wiring pattern provided on at least one of said opposite surfaces and connected to said lands; and

means for maintaining a connection portion between the surface of each of said lands to which said wiring pattern is connected and said wiring pattern in a state not wetted by solder.

2. (Cancelled)

3. (Not Amended) A printed wiring board as claimed in claim 1, wherein said means comprises a material not wetted by the solder coated onto said lands.

4. (Not Amended) A printed wiring board as claimed in claim 3, wherein the material not wetted by the solder is a solder resist.

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Bk
5. (Amended) A printed wiring board as claimed in claim 3, wherein the material not wetted by the solder is a silk-screen pattern.

Alg
6. (Amended) A printing wiring board as claimed in claim 3, wherein the material not wetted by the solder comprises a solder resist and a silk-screen pattern laminated onto each other.

7. (Amended) A printed wiring board as claimed in claim 1, wherein said means comprises deactivation treatment means for oxidizing at least a part of the surface of each of said lands.

8. (Amended) A printed wiring board as claimed in claim 1, wherein lead solder is applied to the leads of the inserted component prior to insertion of the inserted component.